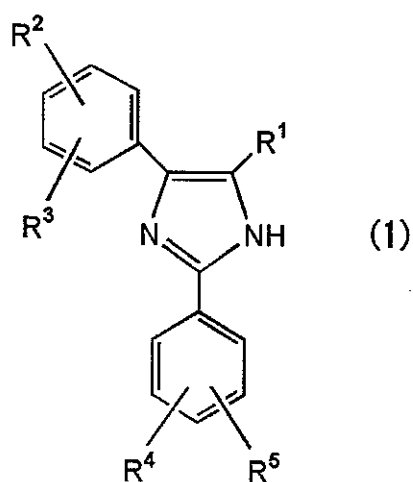


ABSTRACT

A water-based composition for treating copper
or copper alloy surface for lead-free soldering, the
5 composition comprising a compound represented by general
formula (1):



wherein R^1 is hydrogen or methyl, and either R^2 and R^3
represent chlorine and R^4 and R^5 represent hydrogen, or R^2
10 and R^3 represent hydrogen and R^4 and R^5 represent chlorine.